

PICO-BSW1

Intel N3160 / GHz CPU

Thermal Image Analysis Report

Test Cause

For ATRF No. QE160919 Request



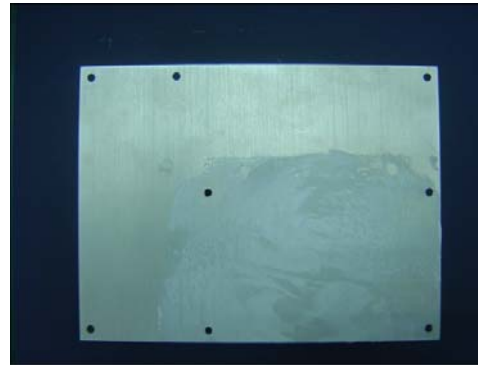
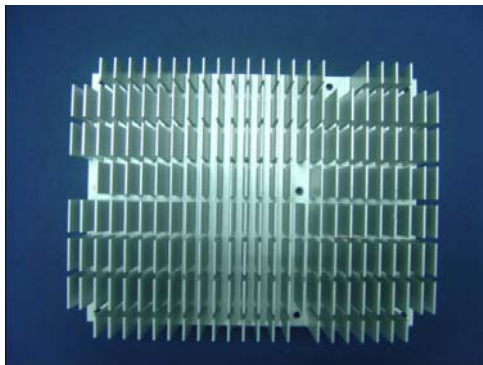
Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation <p style="text-align: center;"><u>Comment: 1. Temperature at 5 component were estimated to be in marginal temperature point in comparion with component datasheets.</u></p>			
Test Result Summary				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	5
Defect Unsolved	0	0	0	5

Issue date	QA Manager	Test Engineer
2016 / 09 / 22	KJ Wang	Juno Cheng

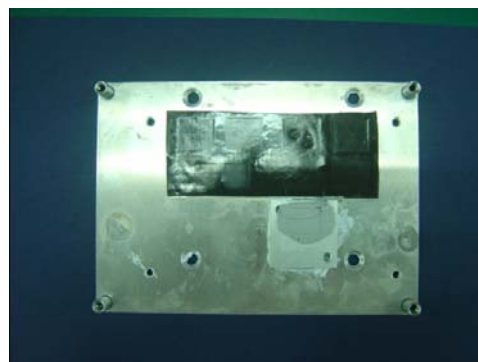
Sample Configuration & Quantity Under Test

- **Model name:** PICO-BSW1 Rev. A0.2
- **CPU:** Intel N3160 / 1.6GHz
- **BIOS:** PICO-BSW1 T0.7 (ZBW1AM07)(08/17/2016)
- **Chipset:** Intel Braswell SOC
- **Memory:** Kingston DDR4 8GB / SKhynix H5AN4G8NAFR TFC
- **2.5" HDD:** TOSHIBA MK1060GSC / 100GB
- **Test Software:** Windows 10/ Run PassMark Burn In Test 8.1 Pro
- **AT Power Supply:** HG2-6400P / 400W
- **Heat Sink:**

Heat Sink (P/N: M16BSW1000)



Heat-Spreader (P/N: M10BT01010) + Thermal Pad



Thermal Image Analysis

1. Test Date: 2016-09-22

2. Test Product: PICO-BSW1

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2016/09/10

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2015/12/01

Serial Number: 1051444

5. Test Condition:

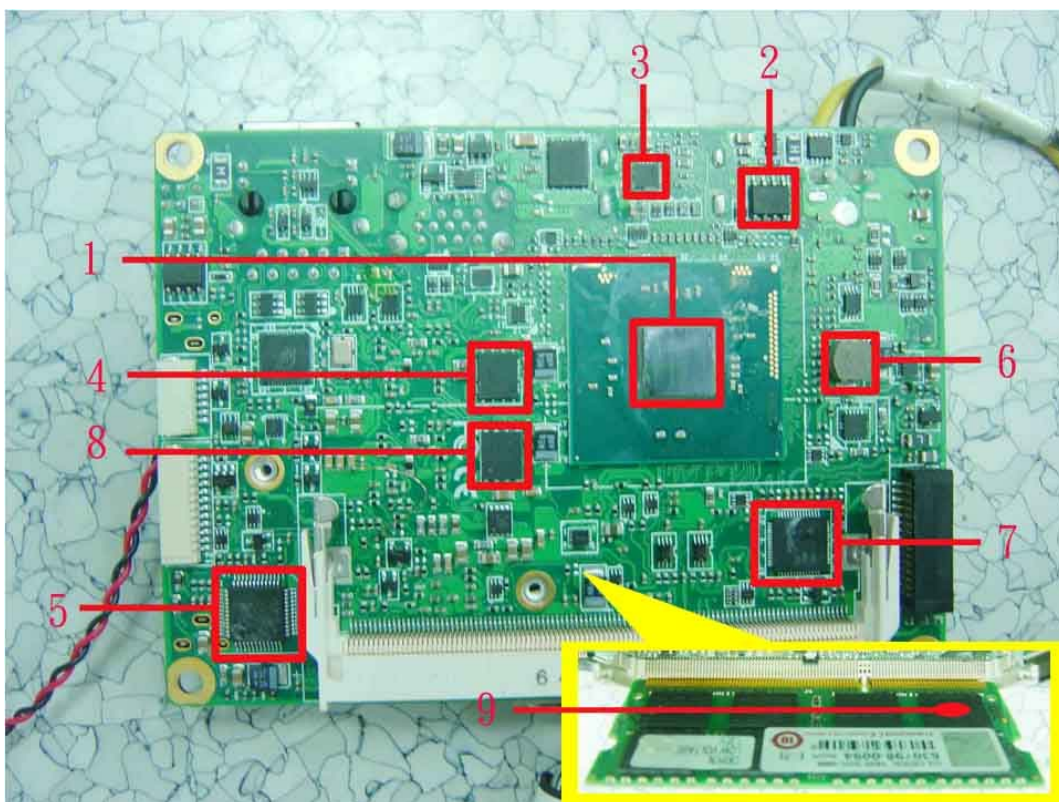
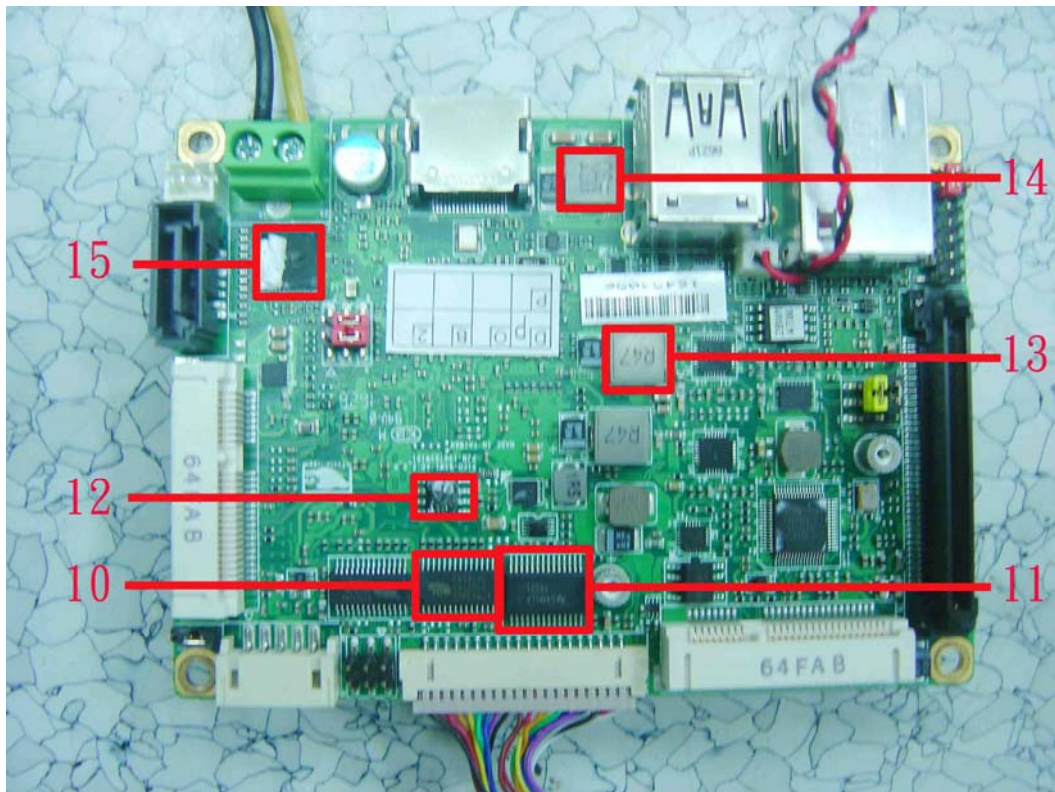
Test by DA-100: 25.0°C with Heat Sink

6. Take Picture Time:

After power on 2 hours

Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2) TPT(*3)		Note
				25.0°C	60°C	
1	U1	Intel Celeron N3160 / 1.6GHz CPU	90	56.3	91.3	Note4
2	U40	RICHTEK.RT9025-25PSP	125	62.4	97.4	
3	U47	TI.TPS53219ARGTR	125	58.3	93.3	
4	Q24	FAIRCHILD.FDMS7620S	125	60.1	95.1	
5	U38	REALTEK.ALC892-CG	100.5	53.0	88.0	Note4
6	L5	NEC/TOKIN.MPLCG0530L1R5	120	56.9	91.9	
7	U7	NXP.PTN3460BS	98.623	60.3	95.3	Note4
8	Q23	ON.NTMFD4C50NT1G	125	57.8	92.8	
9		Memory Chipset	95	53.6	88.6	Note4
10	U36	Fintek.F81438G	125	56.6	91.6	
11	U35	TI.TRS213IDBR	125	55.8	90.8	
12	U42	RICHTEK.RT9025-25PSP	125	60.1	95.1	
13	L3	GOTREND.GSTD6030PE-R47M	125	60.4	95.4	
14	L6	CYNTEC.PCMB063T-1R5MS	125	62.8	97.8	
15	U18	NXP.PTN3360DBS	97.26	57.5	92.5	Note4
16	Air	Air Temperature	N/A	25.0	60.0	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "TAT" indicates the actual measured temperature under 25°C working environmental.
- "TPT" indicates the predicted temperature under product specification.
- Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
- RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
- Defect NO. :